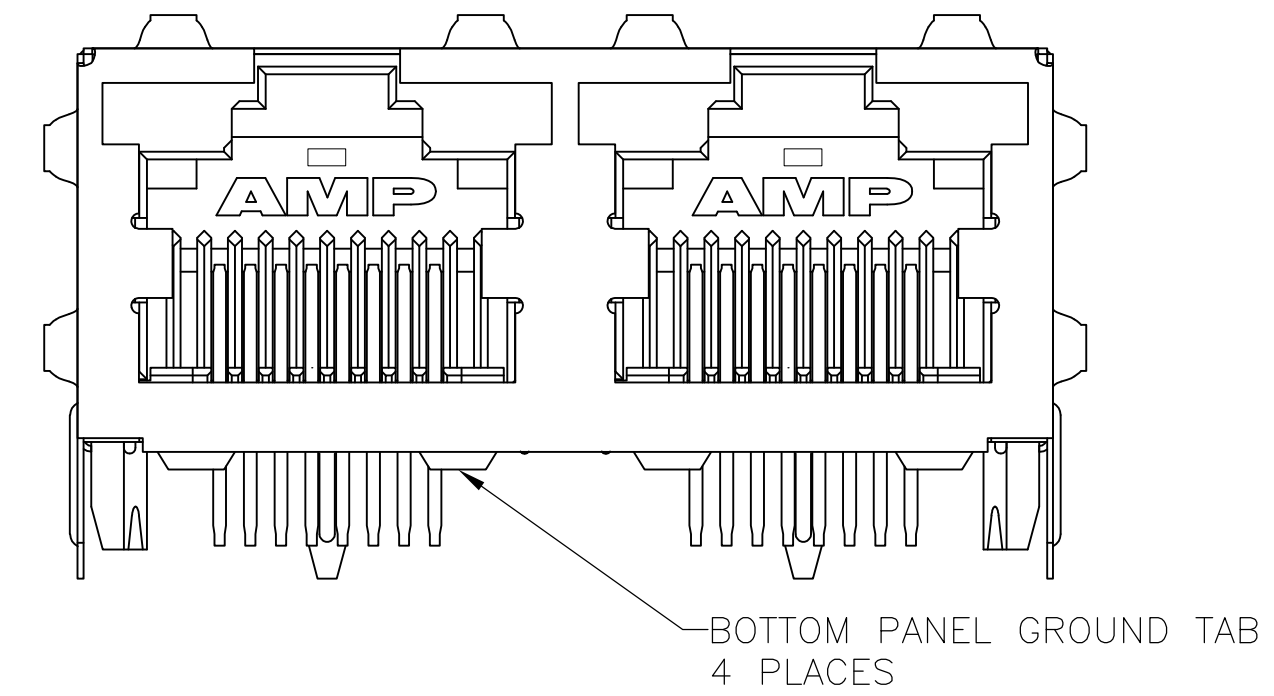
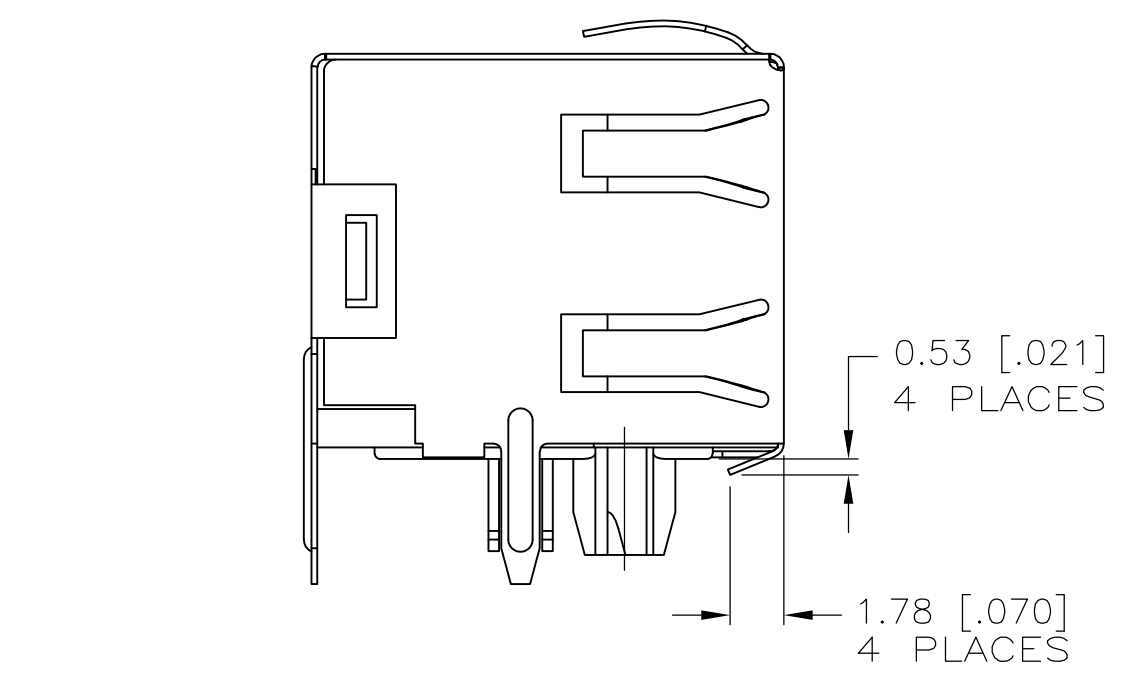
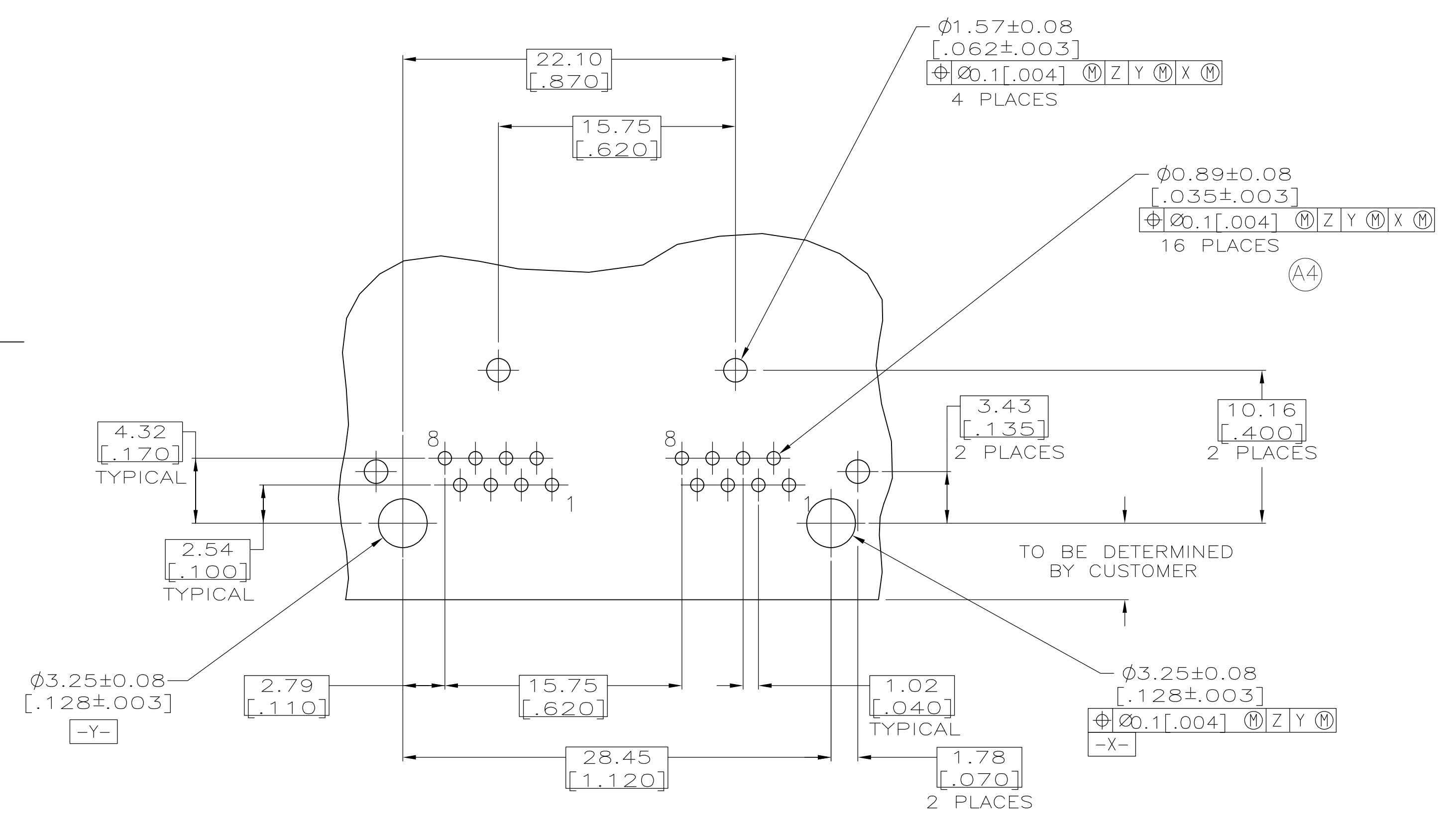


- MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μm [.000050] MINIMUM SATIN NICKEL WITH 2.03 μm [.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ⚠ SUGGESTED PANEL OPENING DIMENSIONS.
 ⚠ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
 ⚠ THE PART IS PRELIMINARY.



PN 6368459-4
 SAME AS PN 6368459-3
 EXCEPT AS SHOWN WITH BOTTOM GROUND PANEL TAB



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

W BOTTOM PANEL GROUND TAB	3.68 [.145]	6368459-4
W/O BOTTOM PANEL GROUND TAB	3.68 [.145]	6368459-3
W/O BOTTOM PANEL GROUND TAB	3.05 [.120]	6368459-1
PANELL GROUND TAB	DIM. A	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN D.L.MAYER 17APR2005	Tyco Electronics Corporation
	0 PLC ± -	CHK J.WESTMAN 17APR2005	Harrisburg, Pa 17105-3608
	1 PLC ± -	APVD S.FLICKINGER 17APR2005	
	2 PLC ± 0.25[.01]		
	3 PLC ± 0.13[.005]		
	4 PLC ± -		
	ANGLES ± -		
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	SIZE A1	00779 C=6368459
		SCALE 4:1	SHEET 1 OF 1
			REV A4

INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND

Mouser Electronics

Authorized Distributor

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[TE Connectivity:](#)

[6368459-1](#)